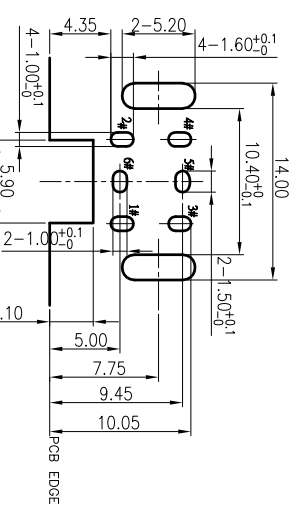
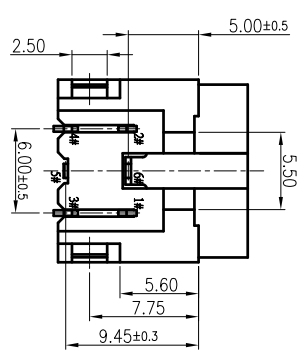
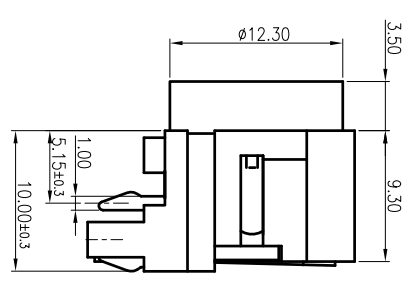
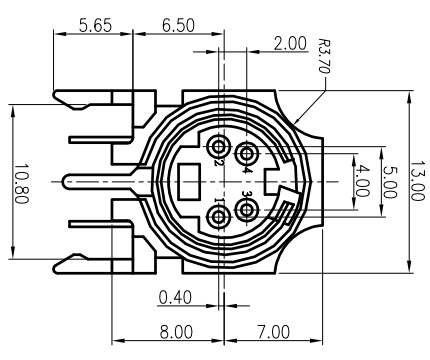
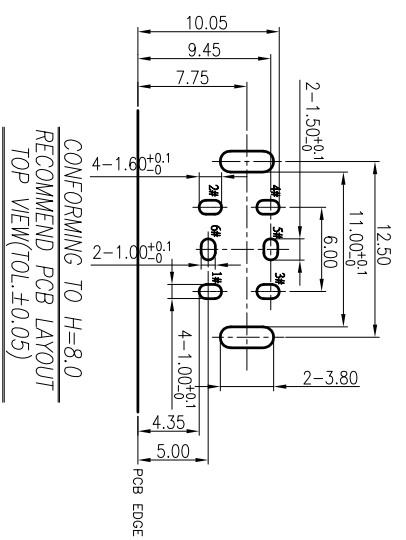
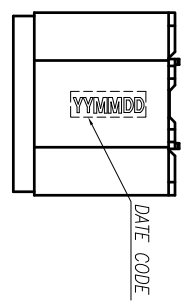
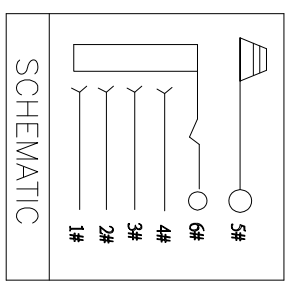


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.: T110211-4A	ARES	2011.02.17



SPECIFICATIONS:

1. WHEN SOLDERING IN THE AUTO SOLDERING BATH IT IS SUGGESTED TO CHECK CONTACT FAILURE, APPEARANCE FAILURE, ETC. BY FLUX BUILD-UP BEFORE.
2. BECAUSE THIS PRODUCT CAN NOT APPLY TO FLUX BUILD-UP PROOF WHEN USING FOR H=6.5.
3. SPECIFICATIONS SEE:
4. MINI DIN CONNECTOR SERIES SPECIFICATIONS
5. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC
6. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
7. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
8. FOR WAVE SOLDERING LEAD-FREE PROCESS.
9. PACKAGING: TRAY.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
D	EARTH SPRING	1	COPPER ALLOY 0.3T	Sn 120u"Min, Ni 50u"MIN
C	CONTACTOR	4	COPPER ALLOY 0.4T	Sn 120u"Min, Ni 50u"MIN
B	EARTH TERMINAL	1	COPPER ALLOY 0.4T	Sn 120u"Min, Ni 50u"MIN
A	BODY	1	HIGH TEMP.THERMOPLASTIC	BLACK
UNLESS OTHERWISE SPECIFIED TOLERANCES				
SINGATRON ENTERPRISE CO., LTD.				
信音企業股份有限公司				
TITLE: Y/C CONNECTOR				
PART NO. 2MJ-0602-005F				
SCALE 2:1 UNIT: mm				
SHEET: 1 OF 1 REV: A				

DECIMALS:	ANGLES:	TITLE	Y/C CONNECTOR
X : ±0.5	X : ±2°	DWN	BILLY 2011.02.25
X.X : ±0.3	X.X : ±1°	CHKD	YIXIAN 2011.02.25
X.XX : ±0.2		APVD	LIAO 2011.02.25
CUSTOMER COPY			